

**SDR6KSMS
and
SDR6MSMS**

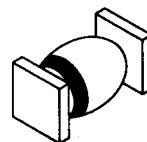
Designer's Data Sheet

FEATURES:

- Ultra Fast Recovery: 60-70 nsec Max. @ 25°C
115-120 nsec Max. @ 100°C
- Single Chip Construction
- PIV to 1000 Volts
- Low Reverse Leakage Current
- Hermetically Sealed Surface Mount package
- Replaces larger DO-4 Rectifiers
- Metallurgically Bonded
- Available in axial leaded versions
- TX, TXV and Space Level Screening Available

**6 AMP
800-1000 VOLTS
60-70 nsec
ULTRA FAST
RECTIFIER**

**SURFACE MOUNT
SQUARE TAB**



MAXIMUM RATINGS

RATING	SYMBOL	VALUE	UNIT
Peak Repetitive Reverse and DC Blocking Voltage SDR6KSMS SDR6MSMS	VRRM VRWM VR	800 1000	Volts
Average Rectified Forward Current (Resistive Load, 60Hz, Sine Wave, TA=25°C)	IO	6	Amps
Peak Surge Current (8.3 ms Pulse, Half Sine Wave Superimposed on IO, allow junction to reach equilibrium between pulses, TA=25°C)	IFSM	150	Amps
Operating and storage temperature	Top & Tstg	-65 to +175	°C
Maximum Thermal Resistance Junction to End Tab	RθJE	8	°C/W

NOTE: All specifications are subject to change without notification.
SCD's for these devices should be reviewed by SSDI prior to release.

DATA SHEET #: RU0099 A

RMD

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PRELIMINARY



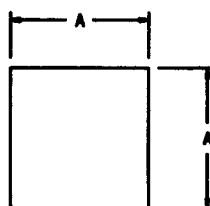
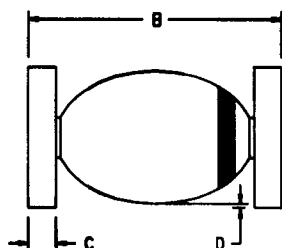
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ELECTRICAL CHARACTERISTICS

CHARACTERISTICS	SYMBOL	MAXIMUM	UNIT
Instantaneous Forward Voltage Drop ($I_F = 6 \text{ A}$, $T_A = 25^\circ\text{C}$, 300 μs Pulse)	V_F	1.9	Vdc
Instantaneous Forward Voltage Drop ($I_F = 6 \text{ A}$, $T_A = -55^\circ\text{C}$, 300 μs Pulse)	V_F	2.1	Vdc
Reverse Leakage Current (Rated V_R , $T_A = 25^\circ\text{C}$, 300 μs pulse minimum)	I_R	10	μA
Reverse Leakage Current (Rated V_R , $T_A = 100^\circ\text{C}$, 300 μs pulse minimum)	I_R	1	mA
Junction Capacitance ($V_R = 10 \text{ Vdc}$, $T_A = 25^\circ\text{C}$, $f = 1 \text{ MHz}$)	C_J	80	pf
Reverse Recovery Time ($I_F = 500 \text{ mA}$, $I_R = 1 \text{ A}$, $I_{RR} = 250 \text{ mA}$, $T_A = 25^\circ\text{C}$)	t_{rr}	60 70	nsec

CASE OUTLINE:



DIMENSIONS

DIM	MIN.	MAX.
A	.195"	.205"
B	.200"	.250"
C	.022"	.028"
D	.002"	—

Dimensions prior to solder dipping.

TYPICAL OPERATING CURVES

$T_A = 25^\circ\text{C}$ Unless otherwise specified

